Winbond Electronics Corp.

32K × 8 HIGH SPEED CMOS STATIC RAM

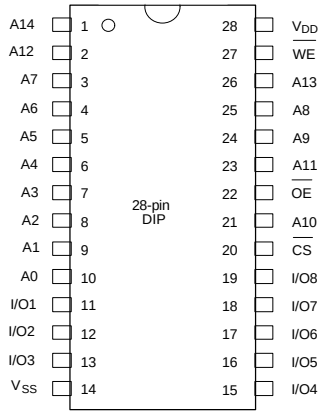
GENERAL DESCRIPTION

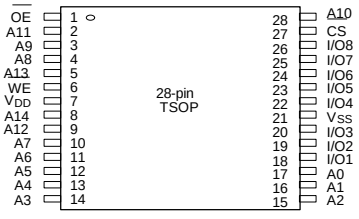
The W24257A is a high speed, low power CMOS static RAM organized as 32768 × 8 bits that operates on a single 5-volt power supply. This device is manufactured using Winbond's high performance CMOS technology.

FEATURES

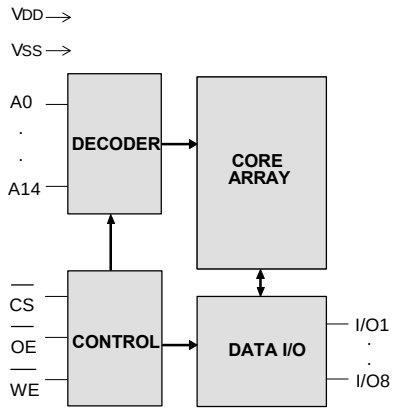
- High speed access time: 10/12/15/20 nS (max.)
- Low power consumption:
  - Active: 400 mW (typ.)
- Single +5V power supply
- Fully static operation
- All inputs and outputs directly TTL compatible
- Three-state outputs
- Available packages: 28-pin 300 mil SOJ, 330 mil SOP, skinny DIP and standard type one TSOP (8 mm × 13.4 mm)

PIN CONFIGURATIONS





BLOCK DIAGRAM



PIN DESCRIPTION

SYMBOL	DESCRIPTION
A0–A14	Address Inputs
I/O1–I/O8	Data Inputs/Outputs
$\overline{CS}$	Chip Select Input
$\overline{WE}$	Write Enable Input
$\overline{OE}$	Output Enable Input
VDD	Power Supply
VSS	Ground

DC CHARACTERISTICS

Absolute Maximum Ratings

PARAMETER	RATING	UNIT
Supply Voltage to V_{SS} Potential	-0.5 to +7.0	V
Input/Output to V_{SS} Potential	-0.5 to V_{DD} +0.5	V
Allowable Power Dissipation	1.0	W
Storage Temperature	-65 to +150	°C
Operating Temperature	0 to +70	°C

Note: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.

TRUTH TABLE

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	MODE	I/O1–I/O8	V_{DD} CURRENT
H	X	X	Not Selected	High Z	I_{SB}, I_{SB1}
L	H	H	Output Disable	High Z	I_{DD}
L	L	H	Read	Data Out	I_{DD}
L	X	L	Write	Data In	I_{DD}

OPERATING CHARACTERISTICS

(V_{DD} = 5V ±10%, V_{SS} = 0V, T_A = 0 to 70° C)

PARAMETER	SYM.	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Input Low Voltage	V_{IL}	-		-0.5	-	+0.8	V
Input High Voltage	V_{IH}	-		+2.2	-	V_{DD} +0.5	V
Input Leakage Current	I_{LI}	V_{IN} = V_{SS} to V_{DD}		-10	-	+10	µA
Output Leakage Current	I_{LO}	$V_{I/O}$ = V_{SS} to V_{DD}, $\overline{CS}$ = V_{IH} or $\overline{OE}$ = V_{IH} or $\overline{WE}$ = V_{IL}		-10	-	+10	µA
Output Low Voltage	V_{OL}	I_{OL} = +8.0 mA		-	-	0.4	V
Output High Voltage	V_{OH}	I_{OH} = -4.0 mA		2.4	-	-	V
Operating Power Supply Current	I_{DD}	$\overline{CS}$ = V_{IL}, I/O = 0 mA Cycle = MIN Duty = 100%	10	-	-	170	mA
			12	-	-	160	mA
			15			150	mA
			20	-	-	140	mA
Standby Power Supply Current	I_{SB}	$\overline{CS}$ = V_{IH} Cycle = MIN, Duty = 100%		-	-	30	mA
	I_{SB1}	$\overline{CS}$ ≥ V_{DD} -0.2V		-	-	10	mA

Note: Typical characteristics are at V_{DD} = 5V, T_A = 25° C.

CAPACITANCE

(V_{DD} = 5V, T_A = 25° C, f = 1 MHz)

PARAMETER	SYM.	CONDITIONS	MAX.	UNIT
Input Capacitance	C_{IN}	V_{IN} = 0V	8	pF
Input/Output Capacitance	$C_{I/O}$	V_{OUT} = 0V	10	pF

Note: These parameters are sampled but not 100% tested.

THERMAL RESISTANCE

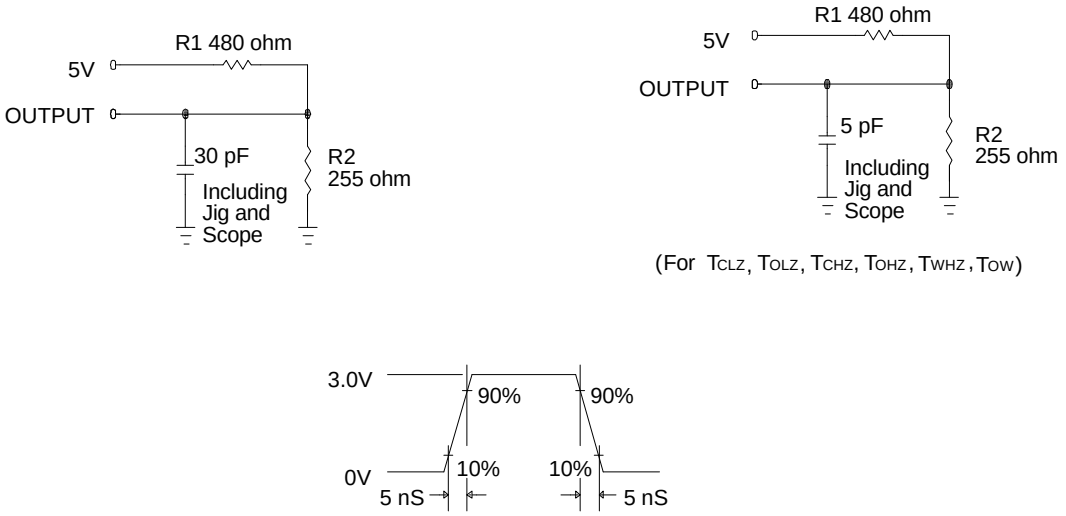
PARAMETER	SYM.	CONDITIONS	MAX.	UNIT
Junction to Case Thermal Resistance	θ_{JC}	A. F. R. = 1m/sec, T_A = 25° C	20	°C/W
Junction to Ambient Thermal Resistance	θ_{JA}	A. F. R. = 1m/sec, T_A = 25° C	60	°C/W

Note: These parameters are only applied to "TSOP" and "SOJ" package types.

AC TEST CONDITIONS

PARAMETER	CONDITIONS
Input Pulse Levels	0V to 3V
Input Rise and Fall Times	5 nS
Input and Output Timing Reference Level	1.5V
Output Load	C_L = 30 pF, I_{OH}/I_{OL} = -4 mA/8 mA

AC TEST LOADS AND WAVEFORM



AC CHARACTERISTICS

(V_{DD} = 5V ±10%, V_{SS} = 0V, T_A = 0 to 70° C)

Read Cycle

PARAMETER	SYM.	W24257A-10		W24257A-12		W24257A-15		W24257A-20		UNIT
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Read Cycle Time	T_{RC}	10	-	12	-	15	-	20	-	nS
Address Access Time	T_{AA}	-	10	-	12	-	15	-	20	nS
Chip Select Access Time	T_{ACS}	-	10	-	12	-	15	-	20	nS
Output Enable to Output Valid	T_{AOE}	-	5	-	6	-	7	-	10	nS
Chip Selection to Output in Low Z	T_{CLZ}*	3	-	3	-	3	-	3	-	nS
Output Enable to Output in Low Z	T_{OLZ}*	0	-	0	-	0	-	0	-	nS
Chip Deselection to Output in High Z	T_{CHZ}*	-	5	-	6	-	7	-	10	nS
Output Disable to Output in High Z	T_{OHZ}*	-	5	-	6	-	7	-	10	nS
Output Hold from Address Change	T_{OH}	3	-	3	-	3	-	3	-	nS

* These parameters are sampled but not 100% tested.

Write Cycle

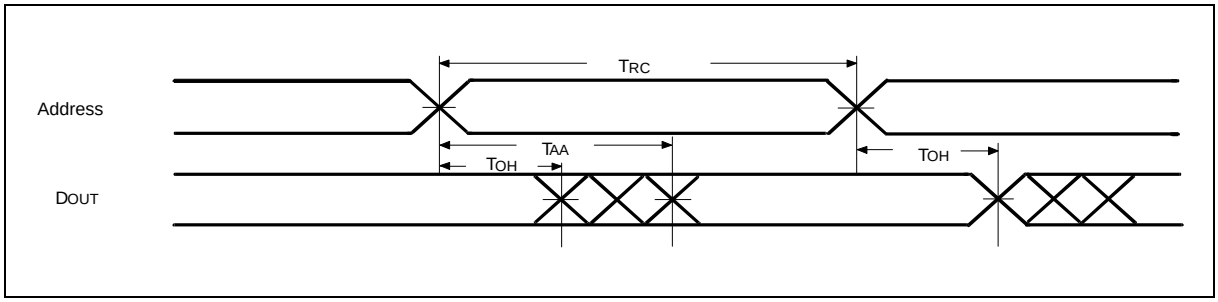
PARAMETER	SYM.	W24257A-10		W24257A-12		W24257A-15		W24257A-20		UNIT
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Write Cycle Time	T_{WC}	10	-	12	-	15	-	20	-	nS
Chip Selection to End of Write	T_{CW}	9	-	10	-	13	-	17	-	nS
Address Valid to End of Write	T_{AW}	9	-	10	-	13	-	17	-	nS
Address Setup Time	T_{AS}	0	-	0	-	0	-	0	-	nS
Write Pulse Width	T_{WP}	9	-	10	-	10	-	12	-	nS
Write Recovery Time ($\overline{CS}$, $\overline{WE}$)	T_{WR}	0	-	0	-	0	-	0	-	nS
Data Valid to End of Write	T_{DW}	6	-	7	-	9	-	10	-	nS
Data Hold from End of Write	T_{DH}	0	-	0	-	0	-	0	-	nS
Write to Output in High Z	T_{WHZ}*	-	6	-	7	-	8	-	10	nS
Output Disable to Output in High Z	T_{OHZ}*	-	6	-	7	-	8	-	10	nS
Output Active from End of Write	T_{OW}	0	-	0	-	0	-	0	-	nS

* These parameters are sampled but not 100% tested.

TIMING WAVEFORMS

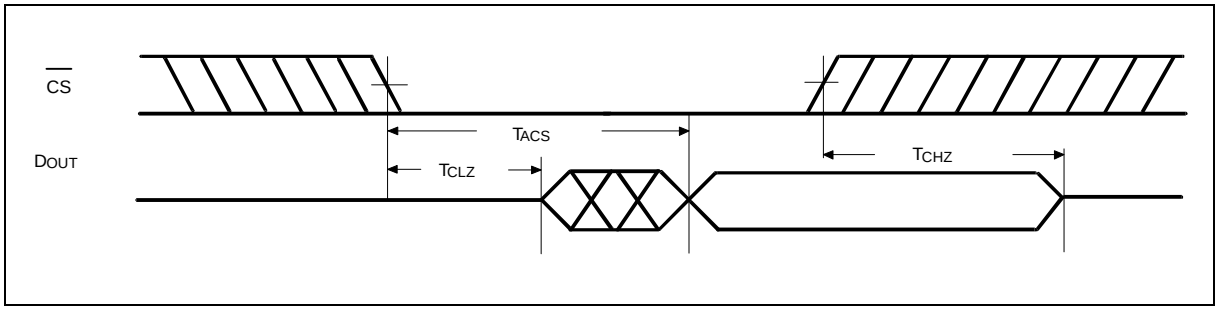
Read Cycle 1

(Address Controlled)



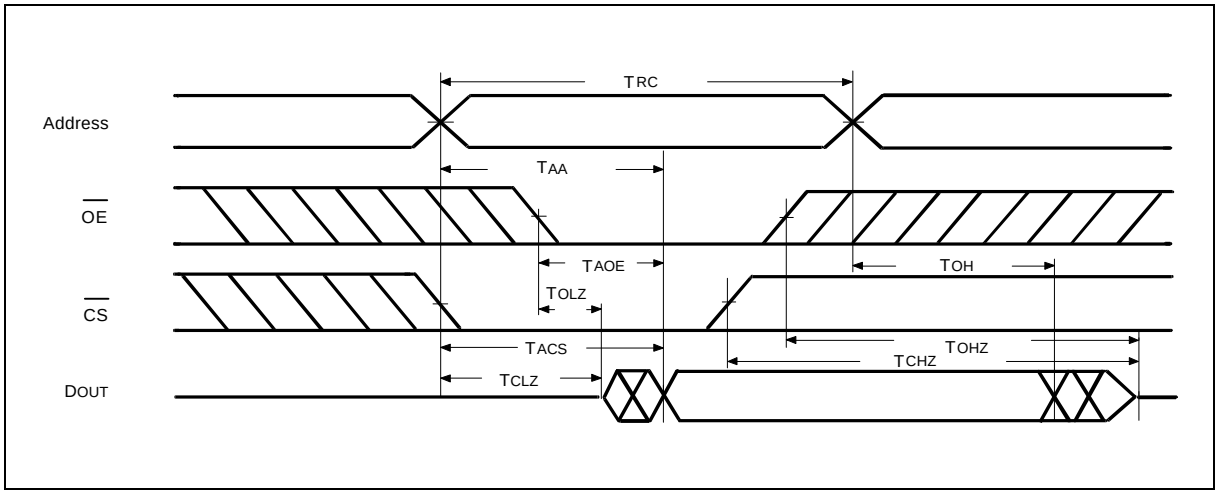
Read Cycle 2

(Chip Select Controlled)



Read Cycle 3

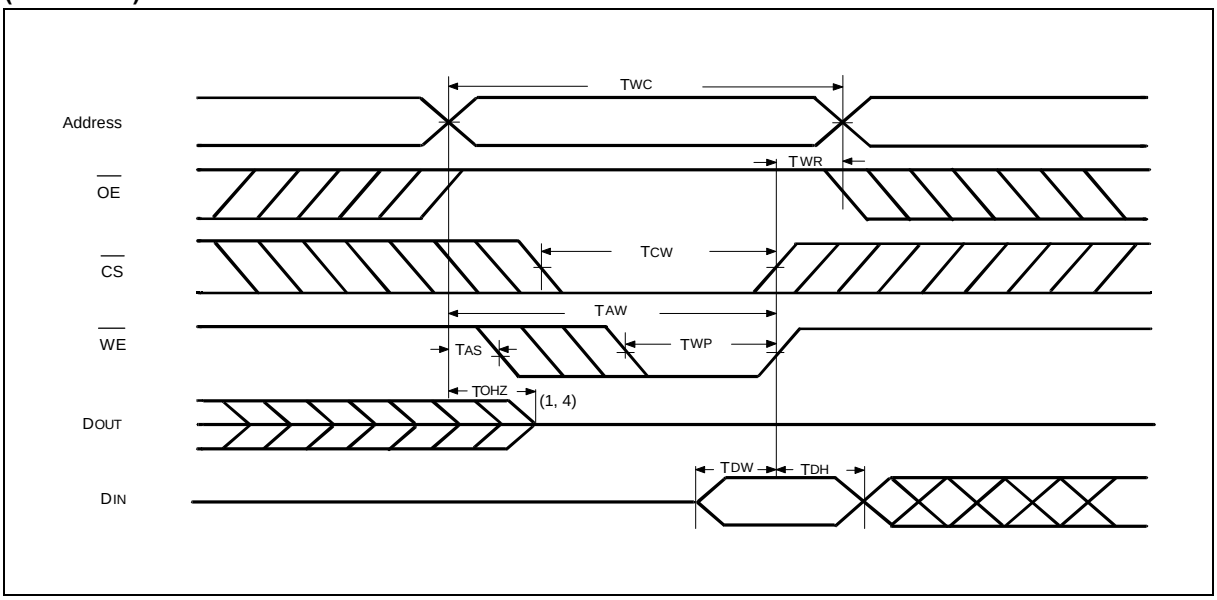
(Output Enable Controlled)



Timing Waveforms, continued

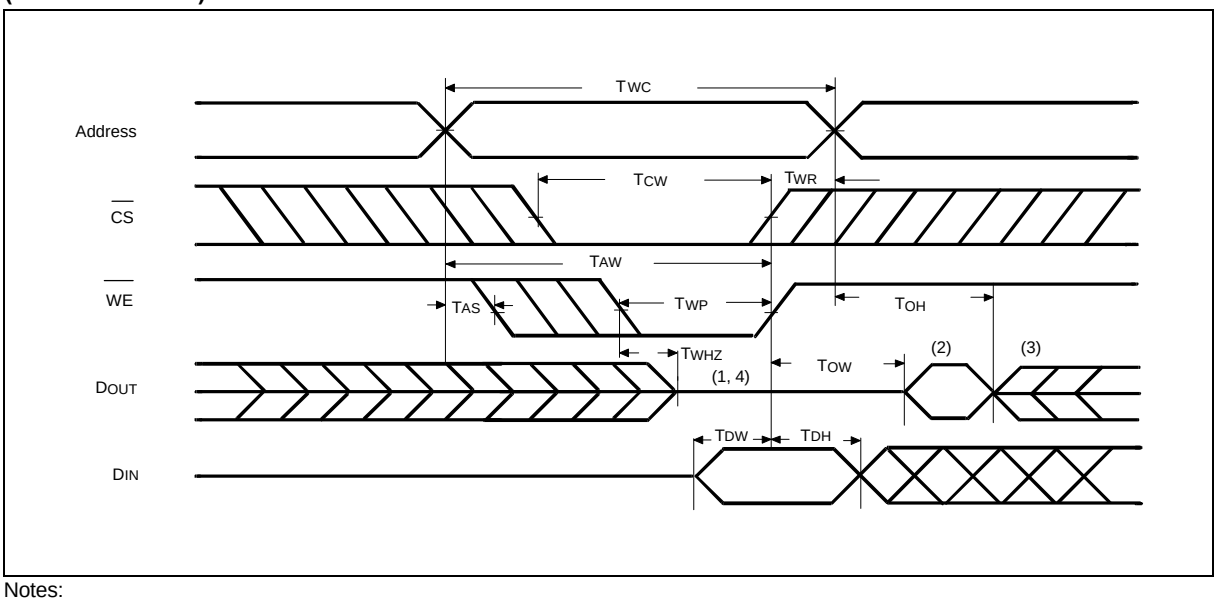
Write Cycle 1

($\overline{OE}$ Clock)



Write Cycle 2

($\overline{OE}$ = VIL Fixed)



Notes:
1. During this period, I/O pins are in the output state, so input signals of opposite phase to the outputs should not be applied.
2. The data output from DOUT are the same as the data written to DIN during the write cycle.
3. DOUT provides the read data for the next address.
4. Transition is measured ±500 mV from steady state with CL = 5 pF. This parameter is guaranteed but not 100% tested.

ORDERING INFORMATION

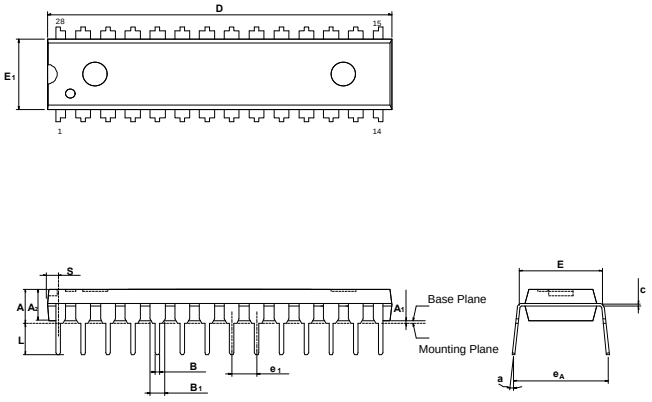
PART NO.	ACCESS TIME (nS)	OPERATING CURRENT MAX. (mA)	STANDBY CURRENT MAX. (mA)	PACKAGE
W24257AK-10	10	170	10	300 mil skinny DIP
W24257AK-12	12	160	10	300 mil skinny DIP
W24257AK-15	15	150	10	300 mil skinny DIP
W24257AK-20	20	140	10	300 mil skinny DIP
W24257AJ-10	10	170	10	300 mil SOJ
W24257AJ-12	12	160	10	300 mil SOJ
W24257AJ-15	15	150	10	300 mil SOJ
W24257AJ-20	20	140	10	300 mil SOJ
W24257AS-10	10	170	10	330 mil SOP
W24257AS-12	12	160	10	330 mil SOP
W24257AS-15	15	150	10	330 mil SOP
W24257AS-20	20	140	10	330 mil SOP
W24257AQ-10	10	170	10	Standard type one TSOP
W24257AQ-12	12	160	10	Standard type one TSOP
W24257AQ-15	15	150	10	Standard type one TSOP
W24257AQ-20	20	140	10	Standard type one TSOP

Notes:

1. Winbond reserves the right to make changes to its products without prior notice.
2. Purchasers are responsible for performing appropriate quality assurance testing on products intended for use in applications where personal injury might occur as a consequence of product failure.

PACKAGE DIMENSIONS

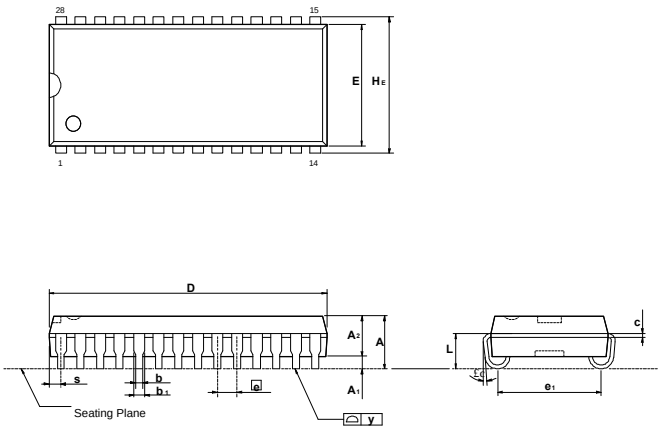
28-pin P-DIP Skinny



Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	—	—	0.175	—	—	4.45
A_1	0.010	—	—	0.25	—	—
A_2	0.125	0.130	0.135	3.18	3.30	3.43
B	0.016	0.018	0.022	0.41	0.46	0.56
B_1	0.058	0.060	0.064	1.47	1.52	1.63
c	0.008	0.010	0.014	0.20	0.25	0.36
D	—	1.388	1.400	—	35.26	35.56
E	0.300	0.310	0.320	7.62	7.87	8.13
E_1	0.283	0.288	0.293	7.19	7.32	7.44
e_1	0.090	0.100	0.110	2.29	2.54	2.79
L	0.120	0.130	0.140	3.05	3.30	3.56
a	0°	—	15°	0°	—	15°
e_A	0.330	0.350	0.370	8.38	8.89	9.40
S	—	—	0.055	—	—	1.40

Notes:
1. Dimensions D Max. & S include mold flash or tie bar burrs.
2. Dimension E1 does not include interlead flash.
3. Dimensions D & E1 include mold mismatch and are determined at the mold parting line.
4. Dimension B1 does not include dambar protrusion/intrusion.
5. Controlling dimension: Inches.
6. General appearance spec. should be based on final visual inspection spec.

28-pin Small Outline J Band

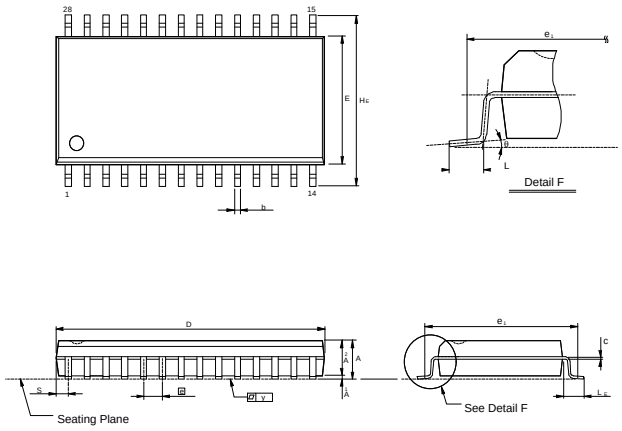


Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	—	—	0.140	—	—	3.56
A_1	0.027	—	—	0.69	—	—
A_2	0.095	0.100	0.105	2.41	2.54	2.67
b_1	0.026	0.028	0.032	0.66	0.71	0.81
b	0.016	0.018	0.022	0.41	0.46	0.56
c	0.008	0.010	0.014	0.20	0.25	0.36
D	—	0.710	0.730	—	18.03	18.54
E	0.295	0.300	0.305	7.49	7.62	7.75
e	0.044	0.050	0.056	1.12	1.27	1.42
e_1	0.245	0.265	0.285	6.22	6.73	7.24
H_E	0.327	0.337	0.347	8.31	8.56	8.81
L	0.077	0.087	0.097	1.96	2.21	2.46
S	—	—	0.045	—	—	1.14
y	—	—	0.004	—	—	0.10
θ	0°	—	10°	0°	—	10°

Notes:
1. Dimensions D Max. & S include mold flash or tie bar burrs.
2. Dimension b does not include dambar protrusion/intrusion.
3. Dimensions D & E include mold mismatch and are determined at the mold parting line.
4. Controlling dimension: Inches.
5. General appearance spec. should be based on final visual inspection spec.

Package Dimensions, continued

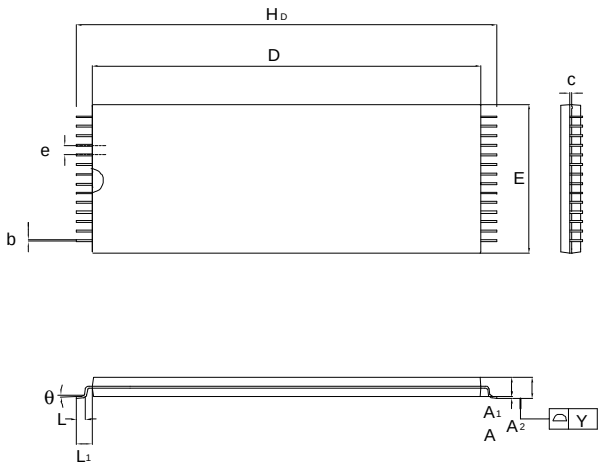
28-pin SO Wide Body



Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	—	—	0.112	—	—	2.85
A_1	0.004	—	—	0.10	—	—
A_2	0.093	0.098	0.103	2.36	2.49	2.62
b	0.014	0.016	0.020	0.36	0.41	0.51
c	0.008	0.010	0.014	0.20	0.25	0.36
D	—	0.713	0.733	—	18.11	18.62
E	0.326	0.331	0.336	8.28	8.41	8.53
e	0.044	0.050	0.056	1.12	1.27	1.42
H_E	0.453	0.465	0.477	11.51	11.81	12.12
L	0.028	0.036	0.044	0.71	0.91	1.12
L_E	0.059	0.067	0.075	1.50	1.70	1.91
S	—	—	0.047	—	—	1.19
y	—	—	0.004	—	—	0.10
q	0°	—	10°	0°	—	10°

Notes:
1. Dimensions D Max. & S include mold flash or tie bar burrs.
2. Dimension b does not include dambar protrusion/intrusion.
3. Dimensions D & E include mold mismatch and are determined at the mold parting line.
4. Controlling dimension: Inches.
5. General appearance spec should be based on final visual inspection spec.

28-pin Standard Type One TSOP



Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	—	—	0.047	—	—	1.20
A_1	0.002	—	0.006	0.05	—	0.15
A_2	0.035	0.040	0.041	0.95	1.00	1.05
b	0.007	0.008	0.011	0.17	0.20	0.27
c	0.004	0.006	0.008	0.10	0.15	0.21
D	0.461	0.465	0.469	11.70	11.80	11.90
E	0.311	0.315	0.319	7.90	8.00	8.10
H_D	0.520	0.528	0.536	13.20	13.40	13.60
e	—	0.022	—	—	0.55	—
L	0.020	0.024	0.028	0.50	0.60	0.70
L_1	—	0.010	—	—	0.25	—
Y	0.000	—	0.004	0.00	—	0.10
q	0	3	5	0	3	5

Note: Controlling dimension: Millimeters

Winbond Electronics Corp.

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